



**THE DATASHEET OF  
SN74HC163IPWRQ1**



# SN74HC163-Q1 4-BIT SYNCHRONOUS BINARY COUNTER

SCLS584A – MAY 2004 – REVISED APRIL 2008

- Qualified for Automotive Applications
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- $\mu$ A Max  $I_{CC}$
- Typical  $t_{pd} = 14$  ns
- $\pm 4$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max
- Internal Look-Ahead for Fast Counting
- Carry Output for n-Bit Cascading
- Synchronous Counting
- Synchronously Programmable

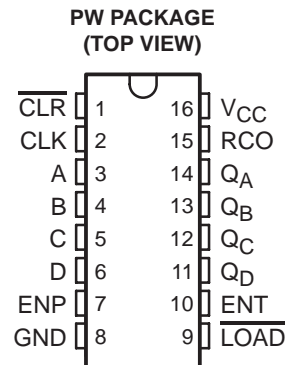
## description/ordering information

This synchronous, presettable counter features an internal carry look-ahead for application in high-speed counting designs. The SN74HC163 is a 4-bit binary counter. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes normally associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

This counter is fully programmable; that is, it can be preset to any number between 0 and 9 or 15. As presetting is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

The clear function for the SN74HC163 is synchronous. A low level at the clear ( $\overline{CLR}$ ) input sets all four of the flip-flop outputs low after the next low-to-high transition of CLK, regardless of the levels of the enable inputs. This synchronous clear allows the count length to be modified easily by decoding the Q outputs for the maximum count desired. The active-low output of the gate used for decoding is connected to  $\overline{CLR}$  to synchronously clear the counter to 0000 (LLLL).

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. ENP, ENT, and a ripple-carry output (RCO) are instrumental in accomplishing this function. Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with  $Q_A$  high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.



## ORDERING INFORMATION†

$T_A$	PACKAGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TSSOP – PW Tape and reel	SN74HC163IPWRQ1	HC163I

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2008 Texas Instruments Incorporated

# SN74HC163-Q1

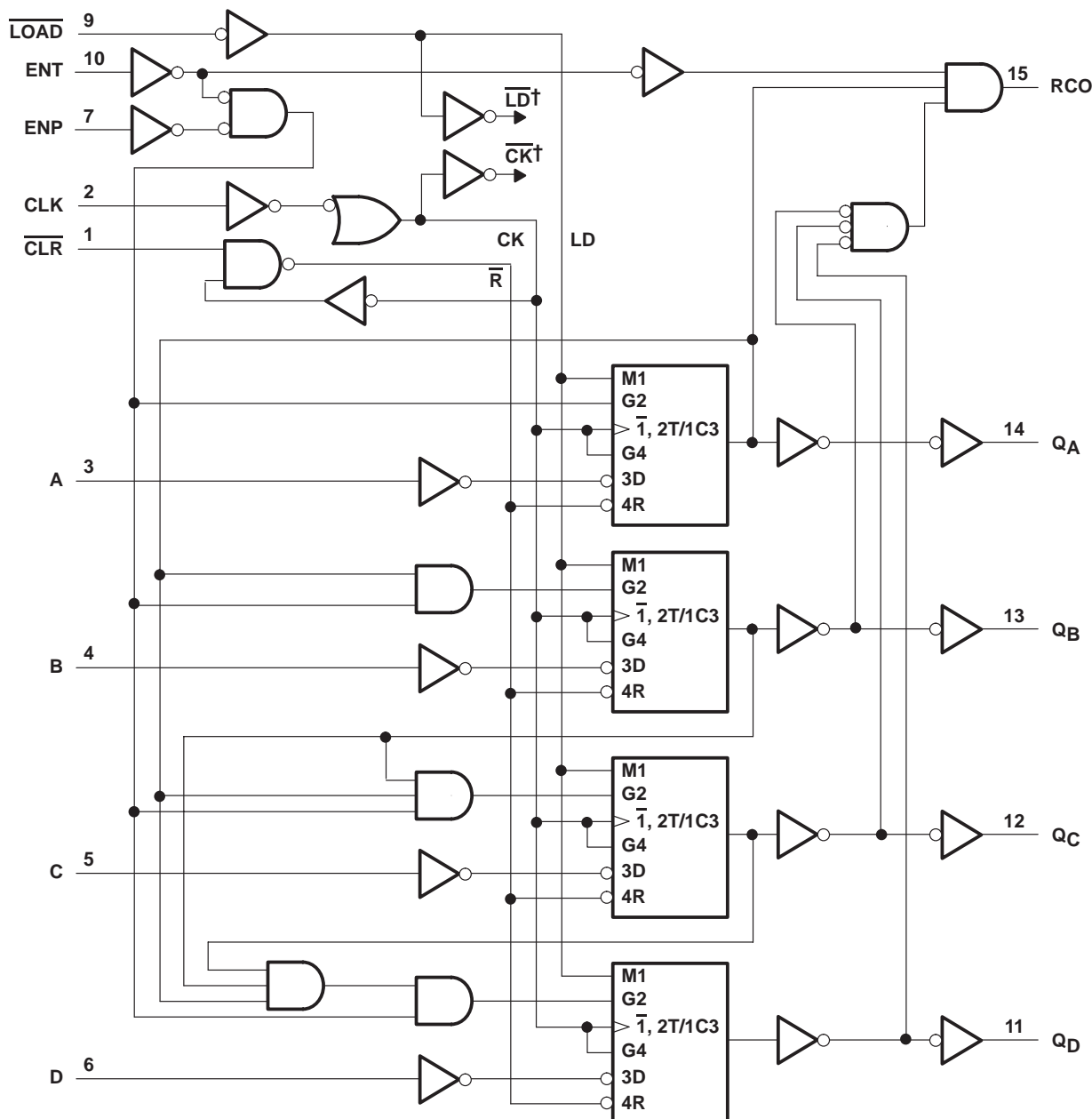
## 4-BIT SYNCHRONOUS BINARY COUNTER

SCLS584A – MAY 2004 – REVISED APRIL 2008

### description/ordering information (continued)

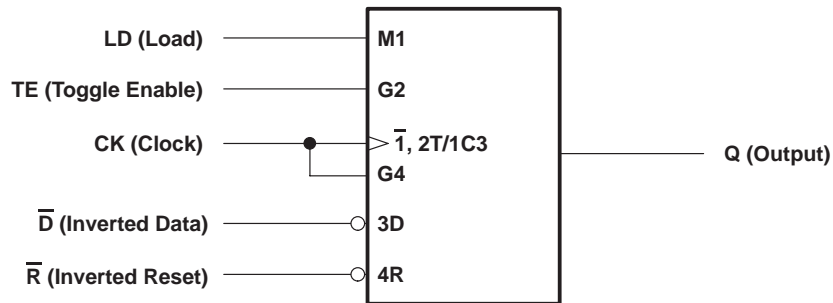
This counter features a fully independent clock circuit. Changes at control inputs (ENP, ENT, or  $\overline{\text{LOAD}}$ ) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

### logic diagram (positive logic)

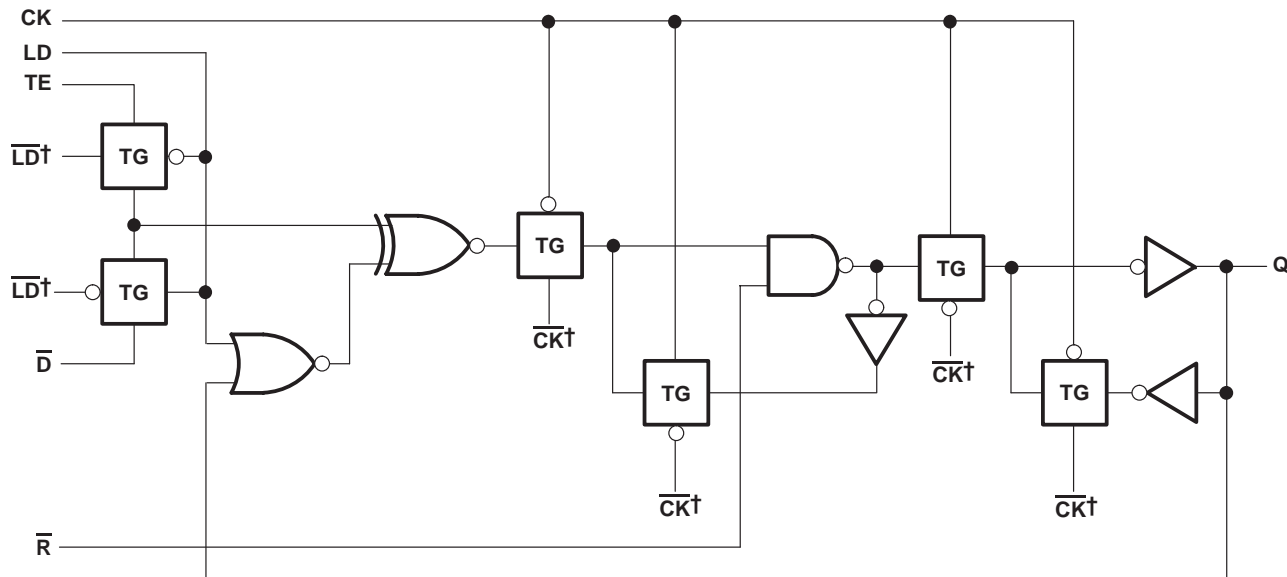


† For simplicity, routing of complementary signals  $\overline{\text{LD}}$  and  $\overline{\text{CK}}$  is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

logic symbol, each D/T flip-flop



logic diagram, each D/T flip-flop (positive logic)



† The origins of  $\overline{LD}$  and  $\overline{CK}$  are shown in the logic diagram of the overall device.

# SN74HC163-Q1

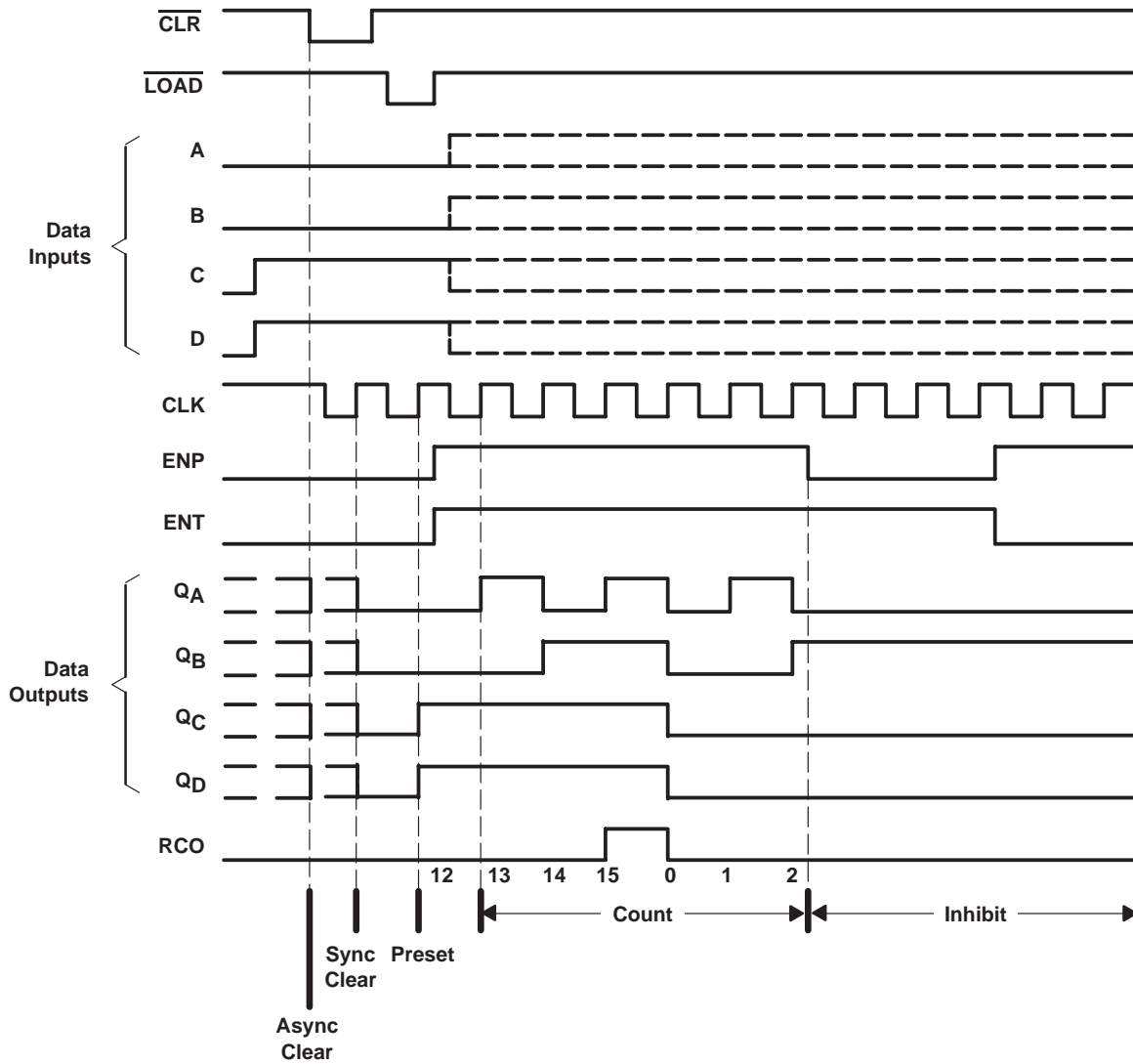
## 4-BIT SYNCHRONOUS BINARY COUNTER

SCLS584A – MAY 2004 – REVISED APRIL 2008

### typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

1. Clear outputs to zero (synchronous)
2. Preset to binary 12
3. Count to 13, 14, 15, 0, 1, and 2
4. Inhibit



# SN74HC163-Q1

## 4-BIT SYNCHRONOUS BINARY COUNTER

SCLS584A – MAY 2004 – REVISED APRIL 2008

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	–0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1) .....	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1) .....	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	±25 mA
Continuous current through $V_{CC}$ or GND .....	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): PW package .....	108°C/W
Storage temperature range, $T_{Stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	2	5	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2$ V	1.5		V
		$V_{CC} = 4.5$ V	3.15		
		$V_{CC} = 6$ V	4.2		
$V_{IL}$	Low-level input voltage	$V_{CC} = 2$ V		0.5	V
		$V_{CC} = 4.5$ V		1.35	
		$V_{CC} = 6$ V		1.8	
$V_I$	Input voltage	0		$V_{CC}$	V
$V_O$	Output voltage	0		$V_{CC}$	V
$\Delta t/\Delta v$ ‡	Input transition rise/fall time	$V_{CC} = 2$ V		1000	ns
		$V_{CC} = 4.5$ V		500	
		$V_{CC} = 6$ V		400	
$T_A$	Operating free-air temperature	–40		85	°C

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

‡ If this device is used in the threshold region (from  $V_{ILmax} = 0.5$  V to  $V_{IHmin} = 1.5$  V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at  $t_f = 1000$  ns and  $V_{CC} = 2$  V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.



# SN74HC163-Q1

## 4-BIT SYNCHRONOUS BINARY COUNTER

SCLS584A – MAY 2004 – REVISED APRIL 2008

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2 V	1.9	1.998	1.9	V	
			4.5 V	4.4	4.499	4.4		
			6 V	5.9	5.999	5.9		
		I <sub>OH</sub> = -4 mA	4.5 V	3.98	4.3	3.84		
			6 V	5.48	5.8	5.34		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V	0.002	0.1	0.1	V	
			4.5 V	0.001	0.1	0.1		
			6 V	0.001	0.1	0.1		
		I <sub>OL</sub> = 4 mA	4.5 V	0.17	0.26	0.33		
			6 V	0.15	0.26	0.33		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0	6 V	±0.1	±100	±1000	nA		
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0	6 V		8	80	μA		
C <sub>i</sub>		2 V to 6 V		3	10	10	pF	

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

	V <sub>CC</sub>	T <sub>A</sub> = 25°C		MIN	MAX	UNIT
		MIN	MAX			
f <sub>clock</sub> Clock frequency	2 V		6		5	MHz
	4.5 V		31		25	
	6 V		36		29	
t <sub>w</sub> Pulse duration	CLK high or low	2 V	80		100	ns
		4.5 V	16		20	
		6 V	14		17	
t <sub>su</sub> Setup time before CLK↑	A, B, C, or D	2 V	150		190	ns
		4.5 V	30		38	
		6 V	26		32	
	LOAD low	2 V	135		170	
		4.5 V	27		34	
		6 V	23		29	
	ENP, ENT	2 V	170		215	
		4.5 V	34		43	
		6 V	29		37	
	CLR low	2 V	160		200	
		4.5 V	32		40	
		6 V	27		34	
	CLR inactive	2 V	160		200	
		4.5 V	32		40	
		6 V	27		34	
t <sub>h</sub> Hold time, all synchronous inputs after CLK↑	2 V	0		0	ns	
	4.5 V	0		0		
	6 V	0		0		



# SN74HC163-Q1

## 4-BIT SYNCHRONOUS BINARY COUNTER

SCLS584A – MAY 2004 – REVISED APRIL 2008

switching characteristics over recommended operating free-air temperature range,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
f <sub>max</sub>			2 V	6	14		5	MHz	
			4.5 V	31	40		25		
			6 V	36	44		29		
t <sub>pd</sub>	CLK	RCO	2 V		83	215		270	ns
			4.5 V		24	43		54	
			6 V		20	37		46	
		Any Q	2 V		80	205		255	
			4.5 V		25	41		51	
			6 V		21	35		43	
	ENT	RCO	2 V		62	195		245	
			4.5 V		17	39		49	
			6 V		14	33		42	
t <sub>t</sub>		Any	2 V		38	75		95	ns
			4.5 V		8	15		19	
			6 V		6	13		16	

operating characteristics, T<sub>A</sub> = 25°C

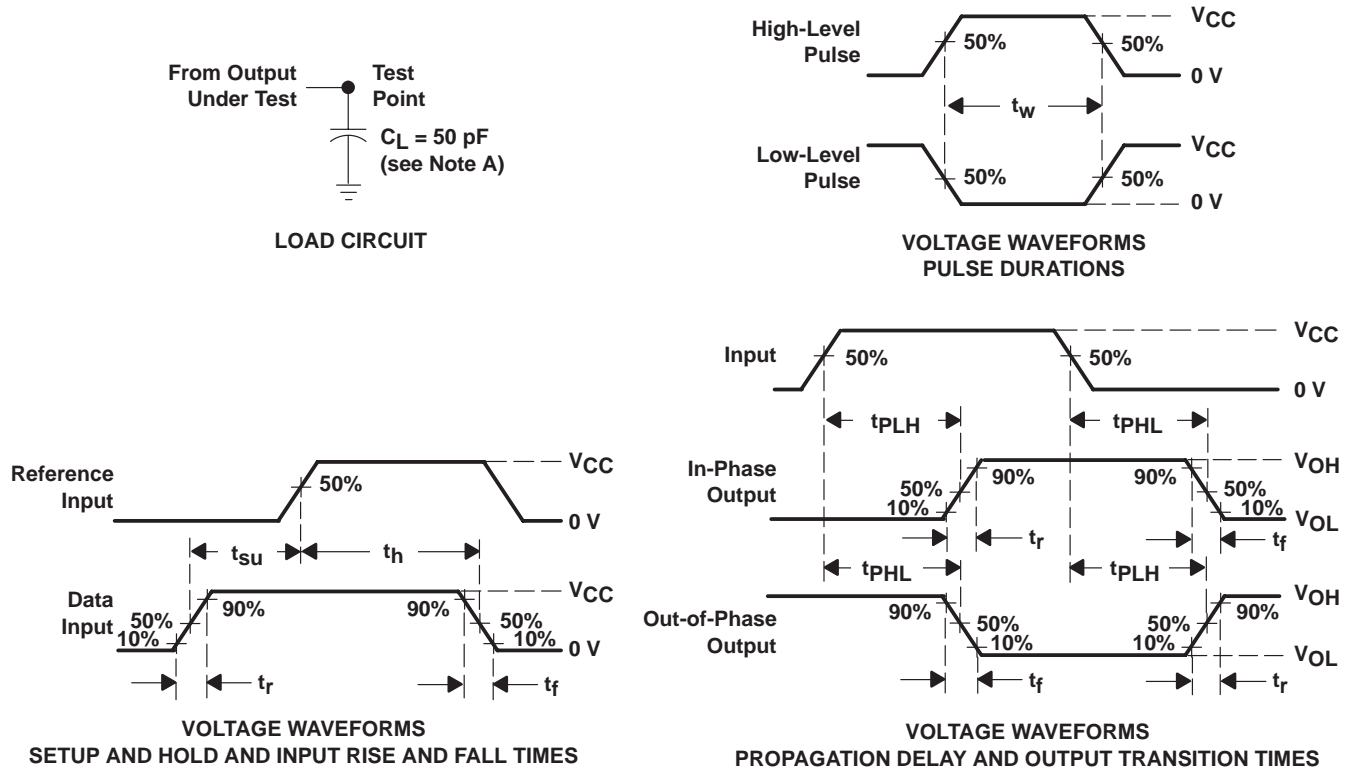
PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	No load	60	pF

# SN74HC163-Q1

## 4-BIT SYNCHRONOUS BINARY COUNTER

SCLS584A – MAY 2004 – REVISED APRIL 2008

### PARAMETER MEASUREMENT INFORMATION



- NOTES:
- $C_L$  includes probe and test-fixture capacitance.
  - Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r = 6 \text{ ns}$ ,  $t_f = 6 \text{ ns}$ .
  - For clock inputs,  $f_{max}$  is measured when the input duty cycle is 50%.
  - The outputs are measured one at a time, with one input transition per measurement.
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

## APPLICATION INFORMATION

### n-bit synchronous counters

This application demonstrates how the look-ahead carry circuit can be used to implement a high-speed n-bit counter. The SN74HC163 counts in binary. Virtually any count mode (modulo-N,  $N_1$ -to- $N_2$ ,  $N_1$ -to-maximum) can be used with this fast look-ahead circuit.

The application circuit shown in Figure 2 is not valid for clock frequencies above 18 MHz (at 25°C and 4.5-V  $V_{CC}$ ). The reason for this is that there is a glitch that is produced on the second stage's RCO and every succeeding stage's RCO. This glitch is common to all HC vendors that Texas Instruments has evaluated, in addition to the bipolar equivalents (LS, ALS, AS).

# SN74HC163-Q1

## 4-BIT SYNCHRONOUS BINARY COUNTER

SCLS584A – MAY 2004 – REVISED APRIL 2008

### APPLICATION INFORMATION

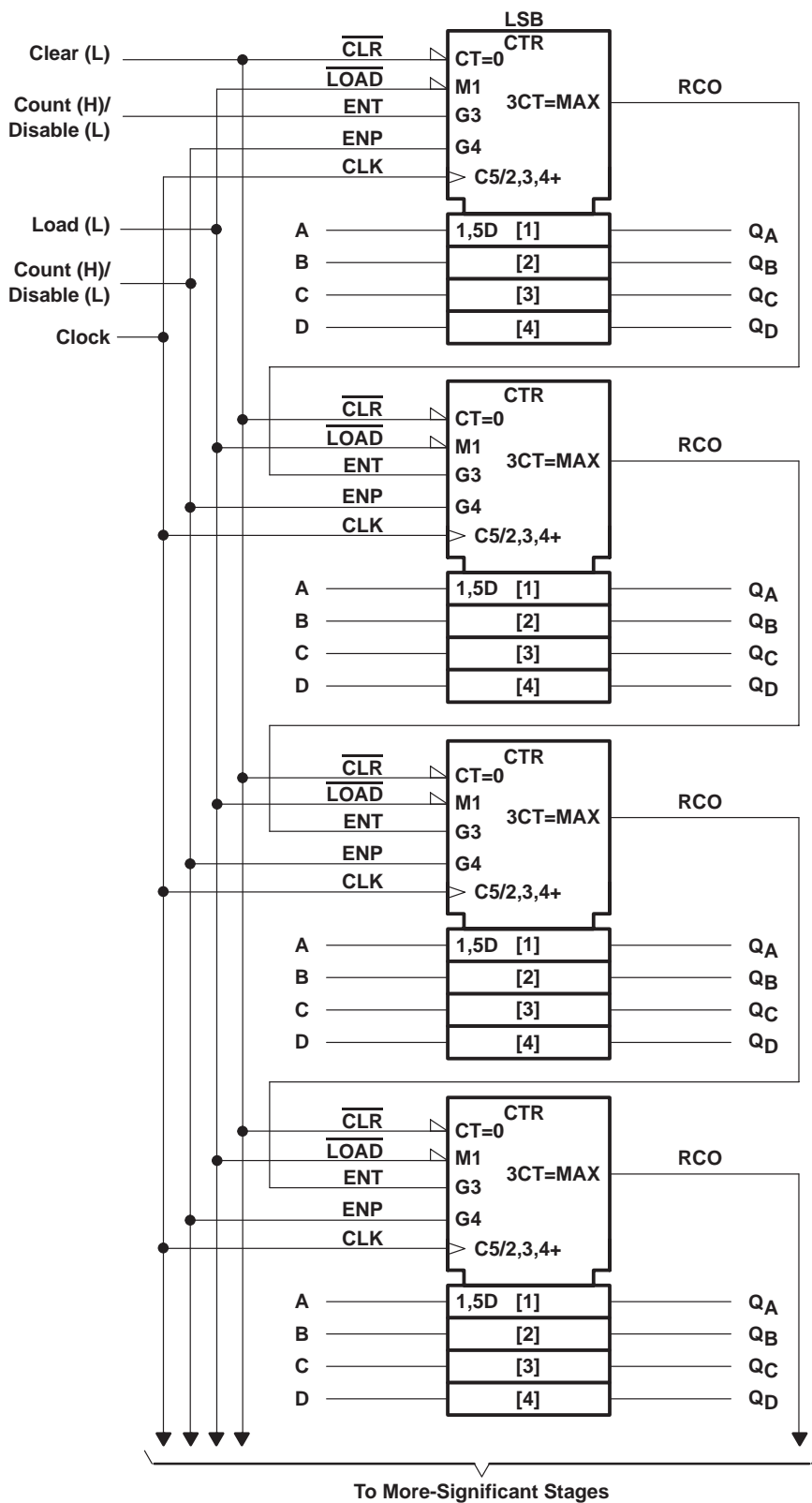


Figure 2

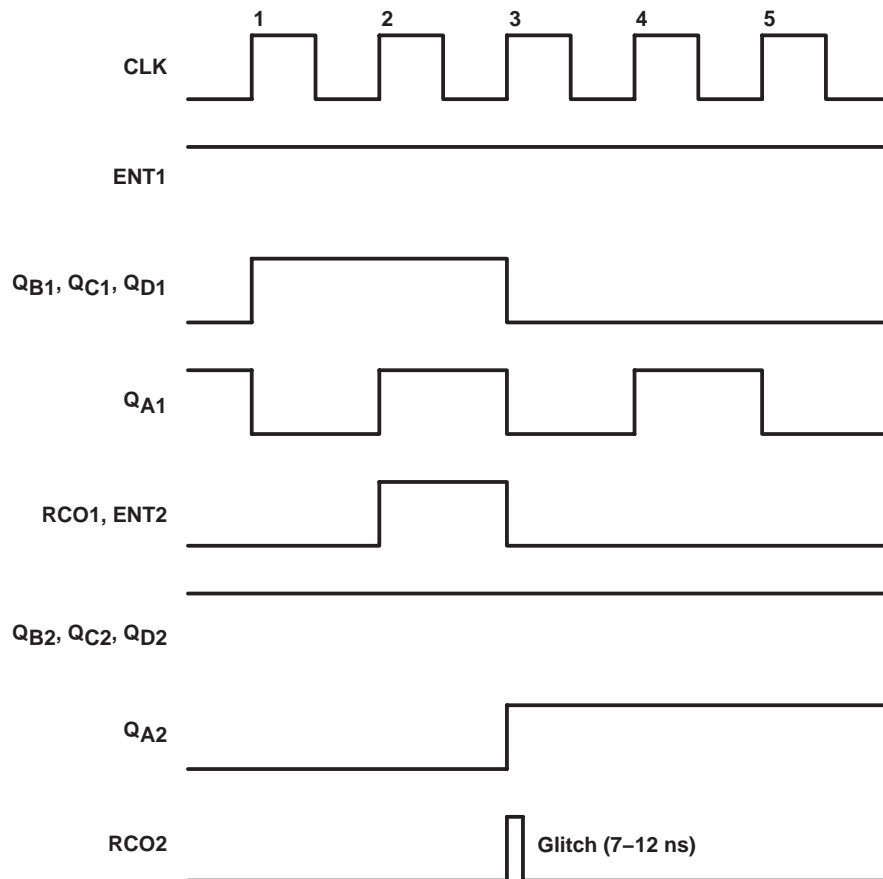


POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

**APPLICATION INFORMATION**

**n-bit synchronous counters (continued)**

The glitch on RCO is caused because the propagation delay of the rising edge of  $Q_A$  of the second stage is shorter than the propagation delay of the falling edge of ENT. RCO is the product of ENT,  $Q_A$ ,  $Q_B$ ,  $Q_C$ , and  $Q_D$  ( $ENT \times Q_A \times Q_B \times Q_C \times Q_D$ ). The resulting glitch is about 7 ns to 12 ns in duration. Figure 3 shows the condition in which the glitch occurs. For simplicity, only two stages are being considered, but the results can be applied to other stages.  $Q_B$ ,  $Q_C$ , and  $Q_D$  of the first and second stage are at logic one, and  $Q_A$  of both stages are at logic zero (1110 1110) after the first clock pulse. On the rising edge of the second clock pulse,  $Q_A$  and RCO of the first stage go high. On the rising edge of the third clock pulse,  $Q_A$  and RCO of the first stage return to a low level, and  $Q_A$  of the second stage goes to a high level. At this time, the glitch on RCO of the second stage appears because of the race condition inside the chip.



**Figure 3**

The glitch causes a problem in the next stage (stage three) if the glitch is still present when the next rising clock edge appears (clock pulse 4). To ensure that this does not happen, the clock frequency must be less than the inverse of the sum of the clock-to-RCO propagation delay and the glitch duration ( $t_g$ ). In other words,  $f_{max} = 1/(t_{pd} \text{ CLK-to-RCO} + t_g)$ . For example, at 25°C at 4.5-V  $V_{CC}$ , the clock-to-RCO propagation delay is 43 ns and the maximum duration of the glitch is 12 ns. Therefore, the maximum clock frequency that the cascaded counters can use is 18 MHz. The following tables contain the  $f_{clock}$ ,  $t_w$ , and  $f_{max}$  specifications for applications that use more than two 'HC163 devices cascaded together.

# SN74HC163-Q1

## 4-BIT SYNCHRONOUS BINARY COUNTER

SCLS584A – MAY 2004 – REVISED APRIL 2008

### APPLICATION INFORMATION

#### n-bit synchronous counters (continued)

#### timing requirements over recommended operating free-air temperature range (unless otherwise noted)

	V <sub>CC</sub>	T <sub>A</sub> = 25°C		MIN	MAX	UNIT
		MIN	MAX			
f <sub>clock</sub> Clock frequency	2 V	3.6		2.9		MHz
	4.5 V	18		14		
	6 V	21		17		
t <sub>w</sub> Pulse duration, CLK high or low	2 V	140		170		ns
	4.5 V	28		36		
	6 V	24		30		

#### switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C		MIN	MAX	UNIT
				MIN	MAX			
f <sub>max</sub>			2 V	3.6		2.9		MHz
			4.5 V	18		14		
			6 V	21		17		

NOTE 4: These limits apply only to applications that use more than two 'HC163 devices cascaded together.

If the SN74HC163 device is used as a single unit, or only two are cascaded together, then the maximum clock frequency that the device can use is not limited because of the glitch. In these situations, the device can be operated at the maximum specifications.

A glitch can appear on the RCO of a single SN74HC163 device, depending on the relationship of ENT to CLK. Any application that uses RCO to drive any input, except an ENT of another cascaded SN74HC163 device, must take this into consideration.



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC163IPWRG4Q1	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC163I	<b>Samples</b>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN74HC163-Q1 :**

- Catalog: [SN74HC163](#)
- Military: [SN54HC163](#)

## NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC163IPWRG4Q1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC163IPWRG4Q1	TSSOP	PW	16	2000	367.0	367.0	35.0



4220204/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale ([www.ti.com/legal/termsofsale.html](http://www.ti.com/legal/termsofsale.html)) or other applicable terms available either on [ti.com](http://ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2018, Texas Instruments Incorporated

## Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View SN74HC163IPWRQ1 on WIN SOURCE](#)

 [Texas Instruments](#) Information

## Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management